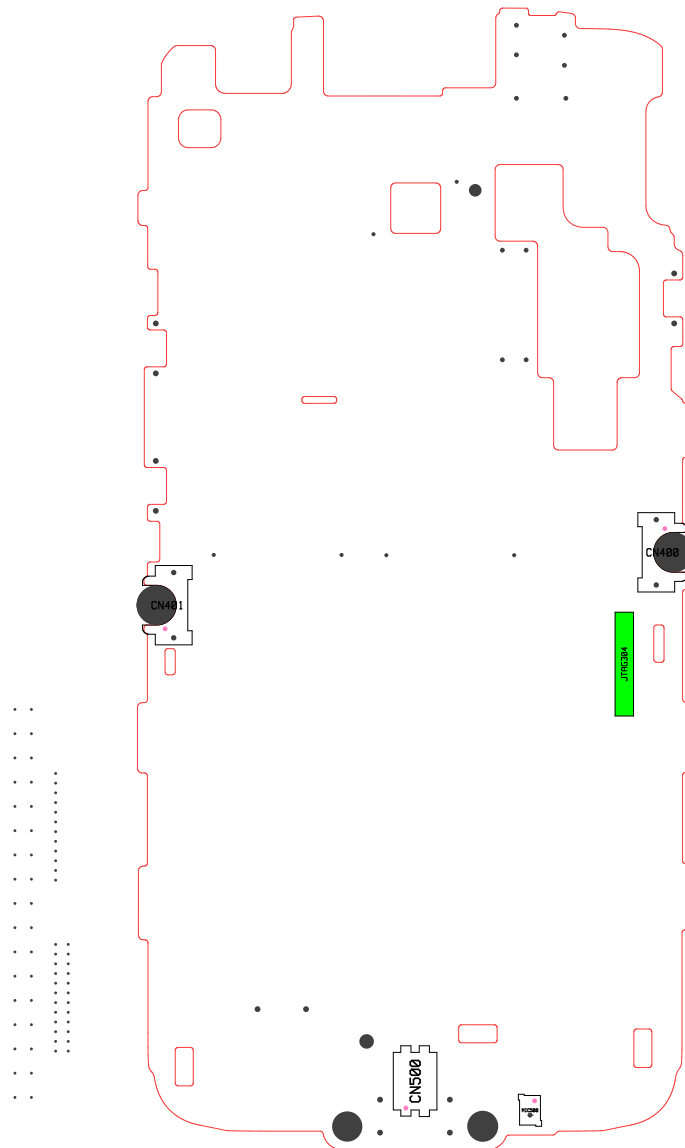


Setup(2015-05-20)_HHP

Model :
Revision :
Manufacture Count :
Charge :
Contact :
Date :
Routing :
Resin :

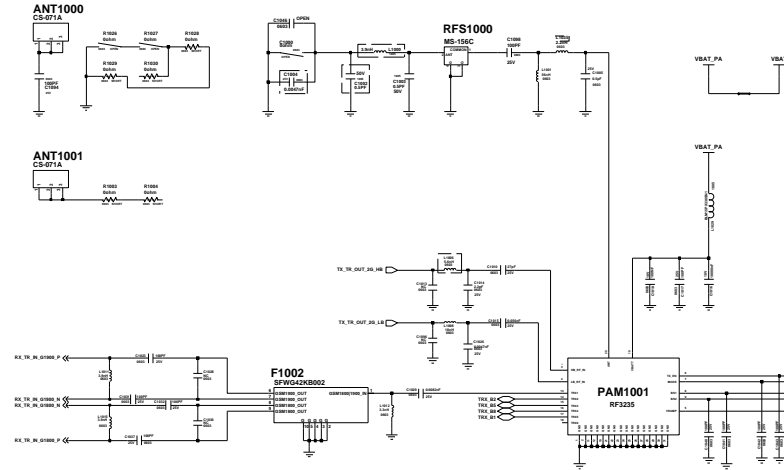


LFB182G45SG9B740(F203) : IT'S

1	2	3	4	5	6	7	8	9	10	11	12
<div><div>SAMSUNG CONFIDENTIAL THIS DOCUMENT CONTAINS CONFIDENTIAL PROPRIETARY INFORMATION THAT IS SAMSUNG ELECTRONICS CO.'S PROPERTY. DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY SAMSUNG.</div><div><h1>SM_J105H_J1_MINI_3G_REV02A</h1><div><div>Page 1 : RF</div><div>Page 2 : GPS, BTWIFIFM</div><div>Page 3 : BBIC</div><div>Page 4 : MEM, MUIC, CHG, BAT CON, IF CON, MOT</div><div>Page 5 : AUDIO, KEY , SIM, SD</div><div>Page 6 : LCD , CAM , SEN</div></div></div></div>											
A											A
B											B
C											C
D											D
E											E
F											F
G											G
H											H
<div><div><div>Changed by Moonhyuk Jung</div><div>Date Changed Thursday, August 27, 2009</div><div>Time Changed 1:18:10 pm</div><div>SA CHK</div><div>REV</div><div>Drawing Number</div><div>Sheet 6 of 8</div></div><div><div>Engineer SAMSUNG</div><div>Drawn by Song</div><div>TITLE TABLE</div><div>Size A2</div></div></div>											
1	2	3	4	5	6	7	8	9	10	11	12

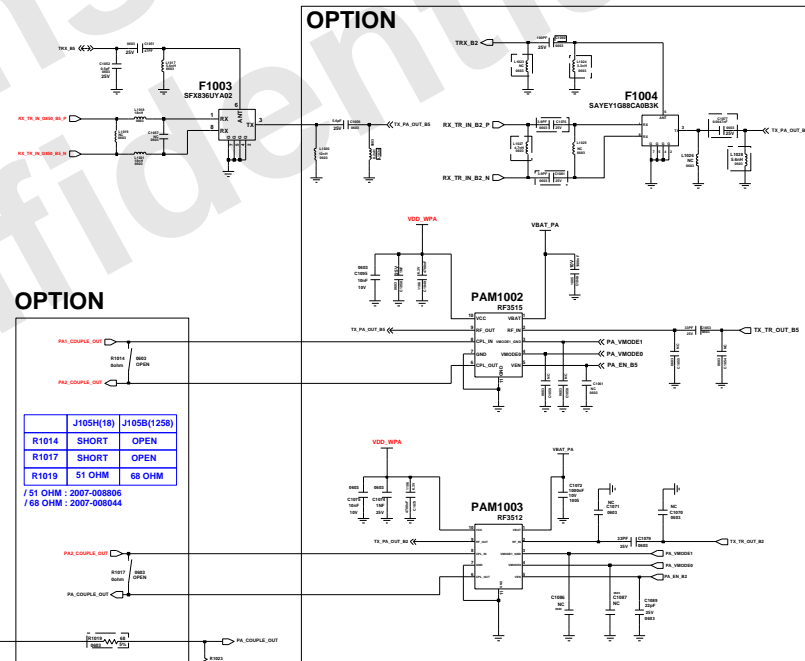
	TX En	Mode	BS1	BS2	VRAMP
Standby	L	L	L	L	L
TRX1_RX (DCS_PCS)	L	H	L	H	X
TRX2_RX (WBS)	L	L	H	L	X
TRX3_TX (WBS) - RX (GSM900)	L	L	L	H	X
TRX4_TX (WBS) - RX (GSM900)	L	L	H	H	X
TRX2_TX (WBS1)	L	H	H	L	X
LB_TX (GSM900_900)	H	L	H	L	Ramp
HR_TX (DCS_PCS)	H	L	L	H	Ramp

	B_1 PA_ENB & PA_EN	VMODE0	VMODE1
Standby Mode	0	0	X
W900_High Power Mode	L	H	X
W900_Mid Power Mode	L	H	H
W900_Low Power Mode	L	H	H
W2100_High Power Mode	H	L	L
W2100_Mid Power Mode	H	L	H
W2100_Low Power Mode	H	L	H



2G PA

3G PA (B1/8)

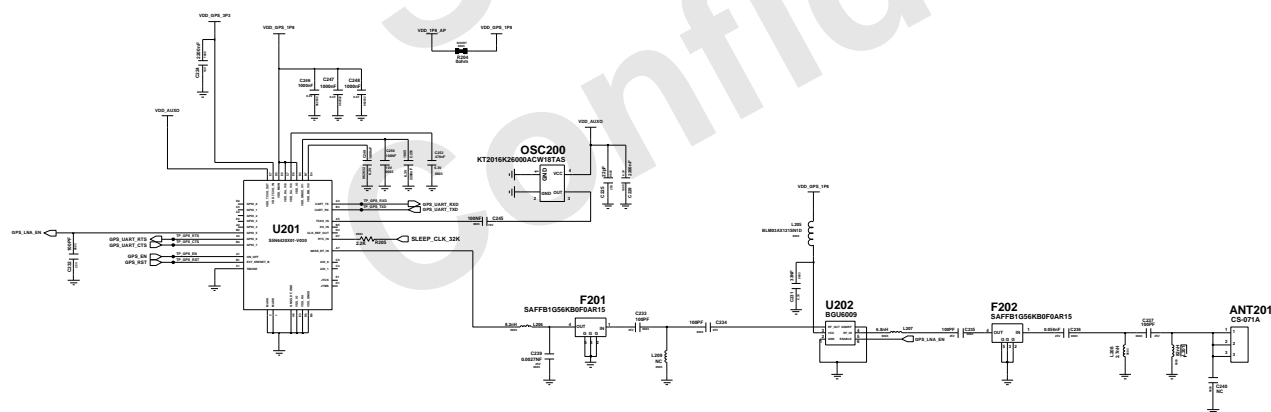
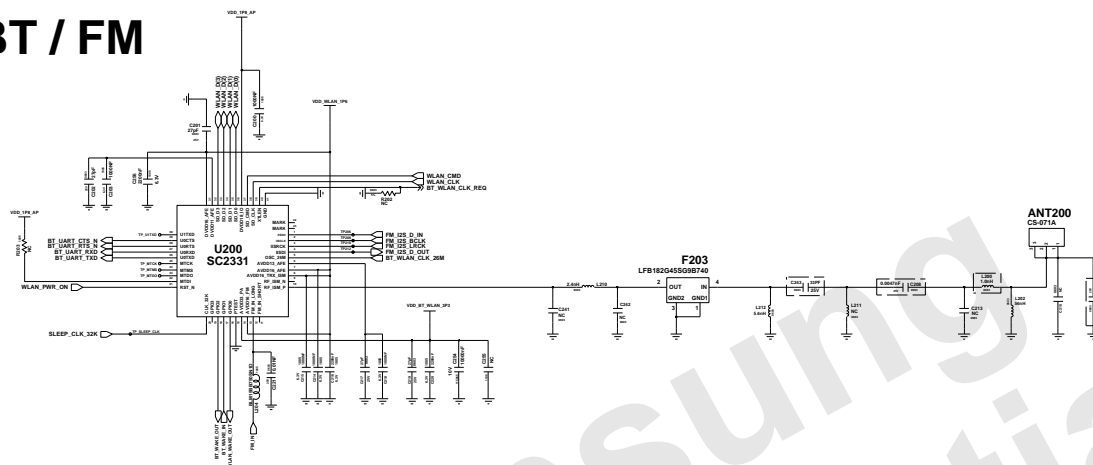


J105H(18) : NC

3G PA B2/5 ONLY

TRCV

Project	Rev	File
25251	1.0	RF
25251	1.0	RF
25251	1.0	RF



GPS

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BBIC

UCP300 SC7727SE

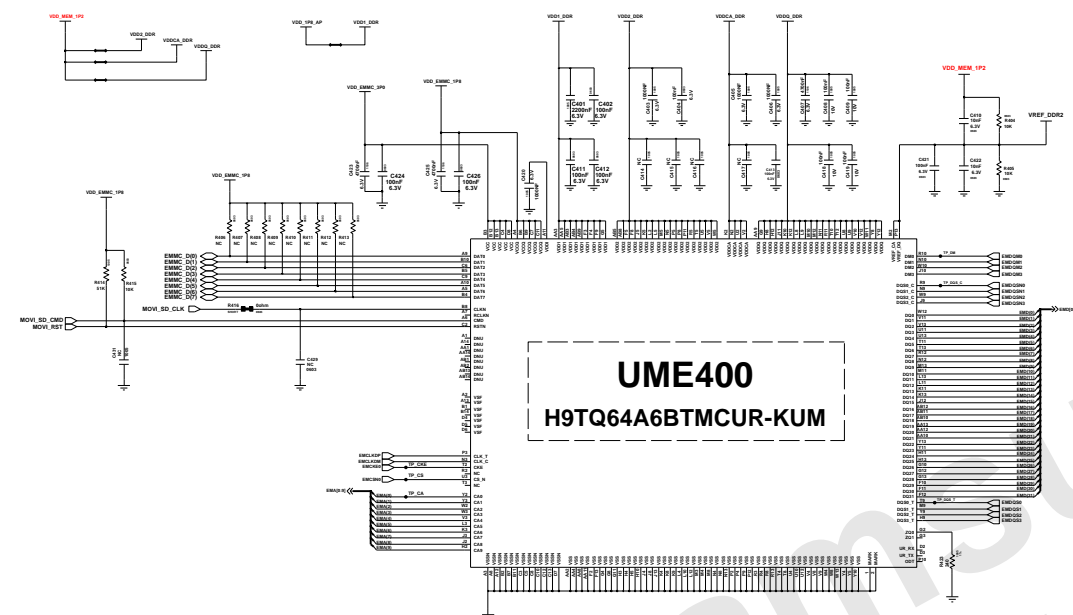
DS
SS
OPTION

	HW_REV0	HW_REV1	HW_REV2
SM_J10SH_REV00	0	0	0
SM_J10SH_REV0A	0	0	1
SM_J10SH_REV01	0	0	1
SM_J10SH_REV01 SOC	0	1	0
SM_J10SH_REV02	0	1	0
SM_J10SH_REV02A_00	0	1	0
SM_J10SH_REV02A_00	0	1	1

ARRAY JTAG

Soldering JTAG PAD

Engineer:		TITLE: BBIC	Size: A			
Drawn by:						
R&D CHK:						
DOC CTRL CHK:						
MFG ENGR CHK:						
Changed by:	Date Changed:	Time Changed:	QA CHK:	REV:	Drawing Number:	Sheet 3 OF 7



OPTION

MEM (8GB EMMC _ 6Gb LPDDR)



THERM

BOTH

OPTION

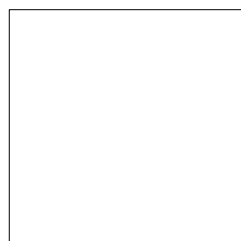
T E B L

	T	E	B	L
SHORT (1)	SS	8G	B1258	NA
OPEN (0)	DS	6G	B18	NA

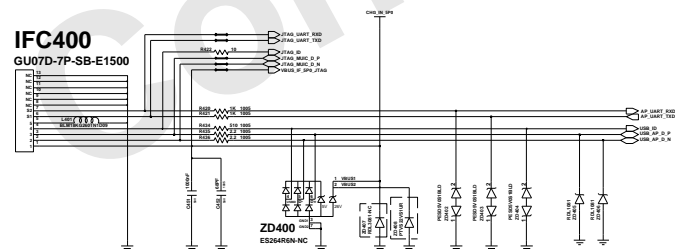
		TEBL		
#1	DS_8G_B18	0100	SM_J105H_DD	SWA_BNG
#2	DS_8G_B18	0000	SM_J105H_DS	MEA_EGY/CIS_S
#3	DS_8G_B1258	0010	SM_J105B_DS	SEA_DX
#4	DS_8G_B1258	0110	SM_J105B_DL	LA_LAX
#5	SS_8G_B18	1000	SM_J105H_SS	MEA_XFA
#6	SS_8G_B1258	1110	SM_J105B_SS	LA_UB

CHG

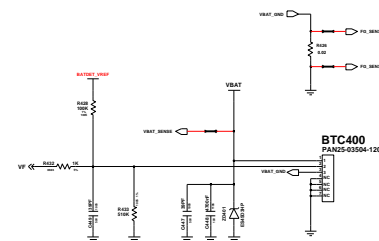
REGION



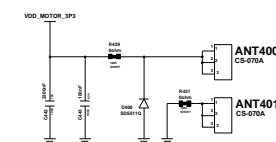
MUIC / OVP



IF CON



BAT CON



MOT PAD

